





(0,80 mm) .0315"

**HSEC8-DV SERIES** 

# VERTICAL EDGE RATE™ CARD SOCKET

### **SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-DV

Insulator Material: Black Liquid Crystal Polymer Contact: BeCu

Plating: Au or Sn over 50μ" (1,27 μm) Ni Current Rating: 2.8 A per pin (2 adjacent pins powered)
Operating Temp: 55°C to +125°C

Card Insertion Depth: (3,15 mm) .125" nominal RoHS Compliant: Yes

### **Processing:**

Lead-Free Solderable: Yes SMT Lead Coplanarity: (0,10 mm) .004" max (10-60)

### **RECOGNITIONS**

For complete scope of recognitions see www.samtec.com/quality





### OTHER **SOLUTIONS**

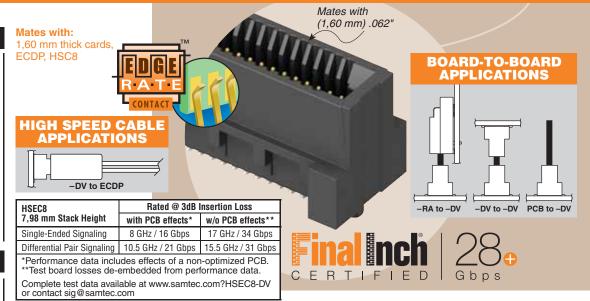
 Standard high speed interface cards for 19 mm, 25 mm & 30 mm mated heights, single-ended & differential applications. See HSC8 Series.

### **ALSO AVAILABLE** (MOQ Required)

- Guide rails
- Pass-through options
- Other platings
- · Custom cards for low-cost stack height customization
- · Samtec supplied card layout/artwork to make your own cards
- Specialty card shapes Contact Samtec.

Note: While optimized for  $50\Omega$ applications, this connector with alternative signal/ground patterns may also perform well in certain  $75\Omega$  applications. Contact Samtec for further information.

Note: Some lengths, styles and options are non-standard, non-returnable.



09, 10, 13, 20, 25, 30, 37, 40, 49

HSEC8

50, 60, 70, 80, 100 (13, 25, 49 only available with -L or -L2 option; 09 only available with -L2 option; 37 only available with -L option)

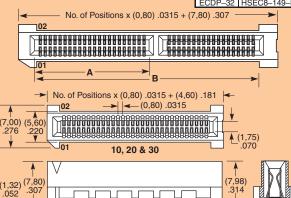
-01 (1,60 mm) .062' thick card

**CARD** 

THICKNESS

-03(2,36 mm) .093 thick card

	CONNECTOR
	HSEC8-109-L2
ECDP-08	HSEC8-113-L2
ECDP-16	HSEC8-125-L2
ECDP-32	HSEC8-149-L2
80) 307 -	



**POSITIONS** 

**PER ROW** 

PLATING

**OPTION** 

= 10μ" (0,25 μm) Gold on contact, Matte Tin on tail

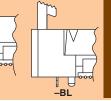
= 30μ" (0,76 μm) Gold on contact, Matte Tin on tail (Requires -80 & -BL)

POSITIONS PER ROW	Α	В
09*†	(4.50) .177	(11,80) .458
13*†	(6,10) .240	(15,00) .591
25*†	(6,10) .240	(24,60) .969
37†	(18,10) .713	(34,20) 1.346
40	(18,90) .744	(36,60) 1.441
49*†	(22,90) .902	(43,80) 1.724
50	(22,90) .902	(44,60) 1.756
60	(26,90) 1.059	(52,60) 2.071
70†	(26,90) 1.059	(60,60) 2.386
80†	(26,90) 1.059	(68,60) 2.701
100†	(26,90) 1.059	(84,60) 3.331

Positions where no dimensions are given do not have keying feature.

Mates with ECDP Series. Available with -01 Card Or

(7.98)



OPTION

(5,50 mm) .217 DIA Polyimide Film Pick & Place Pad

### –BL

= Board Locks (40, 50, 60, 80 only) (Other sizes available. Contact Samtec.)

Latching Option (13, 25, 37, 49 only) (For use with EEDP)

## **-L2**

= ECDP Latching 09, 13, 25, 49 only (For use with ECDP)

> -WT = Weld tab

–TR = Tape & Reel (09 - 70 only)

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

(1.12) .044 DIA

→ No. of Positions x(0,80) .0315 + (2,20) .087